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THERMAL PERFORMANCE						
PARAMETER	SYMBOL	TYP	UNIT			
Junction-to-lead thermal resistance	R _{OJL}	1.5	°C/W			
Junction-to-ambient thermal resistance	R _{eJA}	7.5	°C/W			
Junction-to-case thermal resistance	R _{eJC}	1.0	°C/W			

Thermal Performance Note: Mounted on Heat sink with 4" x 6" x 0.25" Al -Plate.

ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	TYP	МАХ	UNIT
Forward voltage per diode ⁽¹⁾	$I_F = 7.5A, T_J = 25^{\circ}C$	V _F	0.93	-	V
	$I_F = 15A, T_J = 25^{\circ}C$		1.00	1.10	V
	$I_F = 7.5A, T_J = 125^{\circ}C$		0.82	-	V
	I _F = 15A, T _J = 125°C		0.92	-	V
Reverse current @ rated V _R per diode ⁽²⁾	T _J = 25°C	I _R	-	5	μΑ
	T _J = 125°C		-	500	μΑ
Junction capacitance per diode	$1MHz, V_R = 4.0V$	CJ	79	-	pF

Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION				
ORDERING CODE ⁽¹⁾	PACKAGE	PACKING		
GBU150x	GBU	20 / Tube		

Notes:

1. "x" defines voltage from 600V(GBU1505) to 1000V(GBU1507)

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CHARACTERISTICS CURVES

(T_A = 25°C unless otherwise noted)

Fig.1 Forward Current Derating Curve

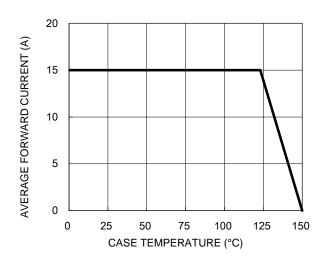


Fig.3 Typical Reverse Characteristics

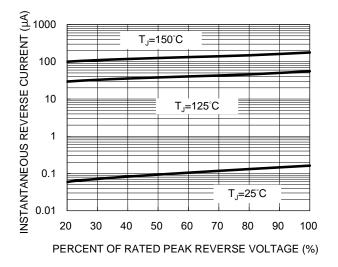


Fig.2 Typical Junction Capacitance

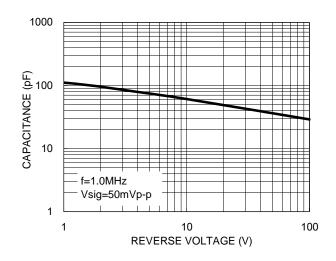
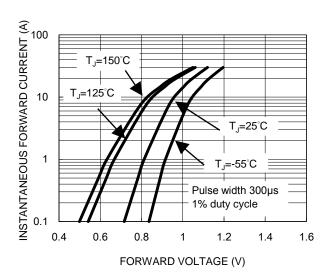


Fig.4 Typical Forward Characteristics



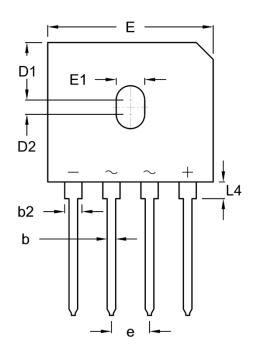
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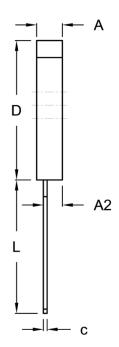
3



PACKAGE OUTLINE DIMENSIONS

GBU





DIM.	Unit (mm)		Unit (inch)	
DIW.	Min.	Max.	Min.	Max.
Α	3.30	3.56	0.130	0.140
A2	2.40	2.66	0.094	0.105
b	1.02	1.27	0.040	0.050
b2	2.06	2.54	0.081	0.100
С	0.46	0.56	0.018	0.022
D	18.30	18.80	0.720	0.740
D1	7.40	7.90	0.291	0.311
D2	1.65	2.16	0.065	0.085
E	21.80	22.30	0.858	0.878
E1	3.50	4.10	0.138	0.161
е	4.83	5.33	0.190	0.210
L	17.50	18.00	0.689	0.709
L4	1.91	2.54	0.075	0.100

MARKING DIAGRAM



P/N = Marking Code G = Green Compound

YWW = Date Code F = Factory Code

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